



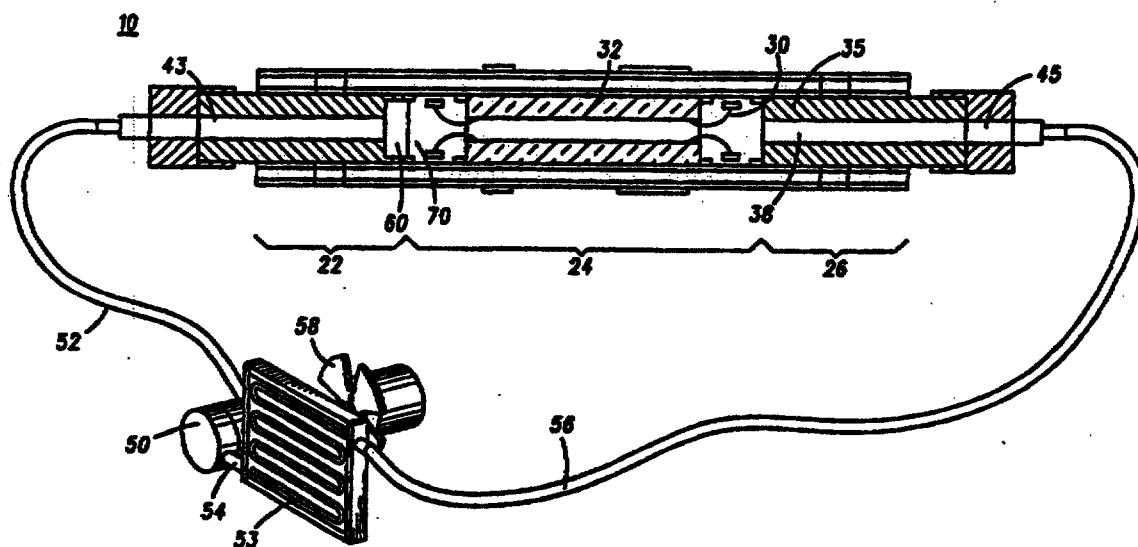
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INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

<p>(51) International Patent Classification ⁶ : H05K 7/20</p>	<p>A1</p>	<p>(11) International Publication Number: WO 98/01015 (43) International Publication Date: 8 January 1998 (08.01.98)</p>
<p>(21) International Application Number: PCT/US97/05341 (22) International Filing Date: 27 March 1997 (27.03.97) (30) Priority Data: 08/674,773 28 June 1996 (28.06.96) US (71) Applicant: MOTOROLA INC. (US/US); 1303 East Algonquin Road, Schaumburg, IL 60196 (US). (72) Inventor: BEISE, Thomas, R.; 806 Concord Lane, Hoffman Estates, IL 60196 (US). (74) Agents: CREPS, Heather, L. et al.; Motorola Inc., Intellectual Property Dept., 1303 East Algonquin Road, Schaumburg, IL 60196 (US).</p>		<p>(81) Designated States: AU, BR, CN, IL, JP, KR, MX, (SG) European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i></p>

(54) Title: **SPRAY-COOLING CIRCUIT BOARD APPARATUS**



(57) Abstract

The circuit board apparatus (10) includes a first layer (12, 14), a second layer (12, 14) and an inner plate (19) disposed between the first layer (12, 14) and the second layer (12, 14). A fluid distributing conduit (38) is disposed in the inner plate (19). The fluid distributing conduit (38) has a first end (22), a central portion (24) defining a chamber, and a second end (26). A first electronic component (28) is disposed within the chamber (24). A nozzle (60) is disposed in the fluid distributing conduit (38). The nozzle (60) receives a fluid, atomizes the fluid and discharges the atomized fluid (70) into the chamber (24).